

METHOD FOR MANUFACTURING MULTILAYER WIRING BOARD

ABSTRACT

5 A method for manufacturing a multilayer wiring board, comprising: a printed wiring board manufacturing step (I) of preparing a plurality of printed wiring boards having both electrical connection pads for establishing an electrical connection between the printed wiring boards and non-connection pads for not establishing an electrical
10 connection between the printed wiring boards on the same plane; and a lamination step (II) of overlaying the plurality of printed wiring boards so that the electrical connection pads face each other, and laminating the printed wiring boards so that the printed wiring boards are bonded to each other through a conductive paste provided between the facing
15 electrical connection pads. In the printed wiring board manufacturing step (I), (Ia) an insulating film is attached to at least one of surfaces faced when the plurality of printed wiring boards are overlaid in the lamination step (II), (Ib) holes are bored in the insulating film so that the electrical connection pads are exposed, and (Ic) a conductive paste is
20 provided in the holes formed in the insulating film by this hole-boring.

Fig. 1